# T2040011060-000 ACTIVE



#### HDC | HDC MM

TE Internal #: T2040011060-000

Pin Contact, Gold, 18 – 8 AWG Wire Size, 1 – 10 mm<sup>2</sup> Wire Size,

Crimp, Copper Alloy, Power & Signal, HDC MM

View on TE.com >



#### Connectors > Contacts > Connector Contacts



Contact Type: Pin

Contact Mating Area Plating Material: Gold

Wire Contact Termination Area Plating Material: Gold

Wire Size: 1 – 10 mm<sup>2</sup>

#### **Features**

## **Product Type Features**

Discrete Wire Type	Solid or Stranded
Sealable	No
Contact Features	
Contact Mating Area Plating Material Finish	Bright

Contact Mating Area Plating Material Finish	Bright
Contact Underplating Material	Copper
Contact Type	Pin
Contact Mating Area Plating Material	Gold
Wire Contact Termination Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	40 A

#### **Termination Features**

Termination Method to Wire & Cable	Crimp
Product Terminates To	Wire & Cable
Dimensions	

Wire Size	$1 - 10 \text{ mm}^2$	

#### Operation/Application

Compatible With Wire Base Material	Copper
Circuit Application	Power & Signal



### **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant with Exemptions
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) SVHC > Threshold: Pb (3.7% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

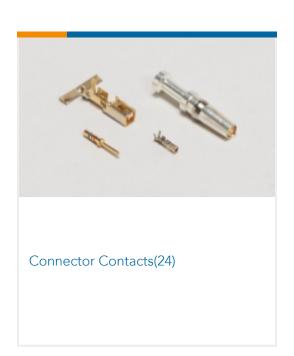
# Compatible Parts





Also in the Series | HDC MM





# Customers Also Bought















## **Documents**

## **Product Drawings**

DMM-6.0

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_T2040011060-000\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_T2040011060-000\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_T2040011060-000\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Pin Contact, Gold, 18-8 AWG Wire Size, 1-10 mm $^2$  Wire Size, Crimp, Copper Alloy, Power & Signal, HDC MM



Datasheets & Catalog Pages

**HEAVY DUTY CONNECTORS** 

English

**HEAVY DUTY CONNECTORS** 

Japanese

**Product Specifications** 

**Application Specification** 

English